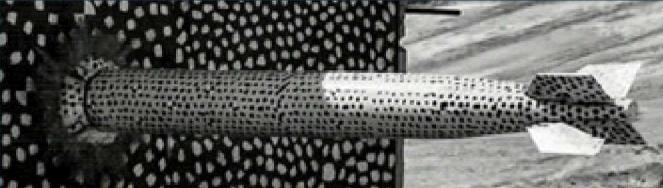


Methods of Depositing Anti-reflective Coatings for Additively Manufactured Optics



PRESENTED BY

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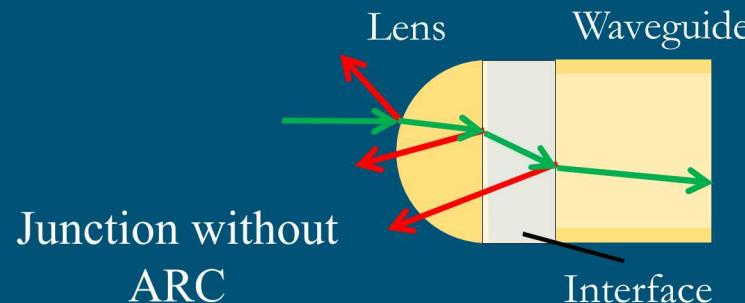
†Integrated Deposition Solutions, Inc.

Outline

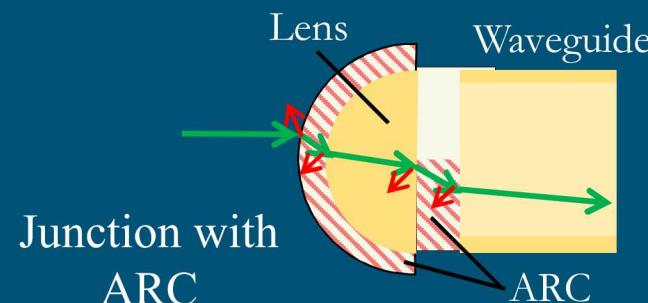
- Motivation
- Technical Background
- Selected Materials
- Experimental Procedure
- Film Characterization
- Future Work
- Conclusion

Motivation

- Complex micro-optic systems offer many opportunities for advanced sensing and communications
- Reflections generated at interfaces increase signal loss and feedback
- Anti-reflective coatings (ARCs) are implemented to reduce reflection and improve system function
- Traditional ARCs are typically deposited via atomic layer deposition
 - Non-selective process, exposes entire system to coating material
- Goal: Develop an additive method to selectively deposit anti-reflective coating



Incident light
Reflected light;
signal loss, noise



Technical Background – ARC Design

- Thin films produce destructive interference of reflected rays of light
- Film parameters for best anti-reflection properties given by:

$$n_f = \sqrt{n_o * n_s}$$

$$d_f = \frac{k * \lambda}{4 * n_f}$$

○ This study focused on a wavelength of 850 nm

n_f -Refractive index (RI) of film

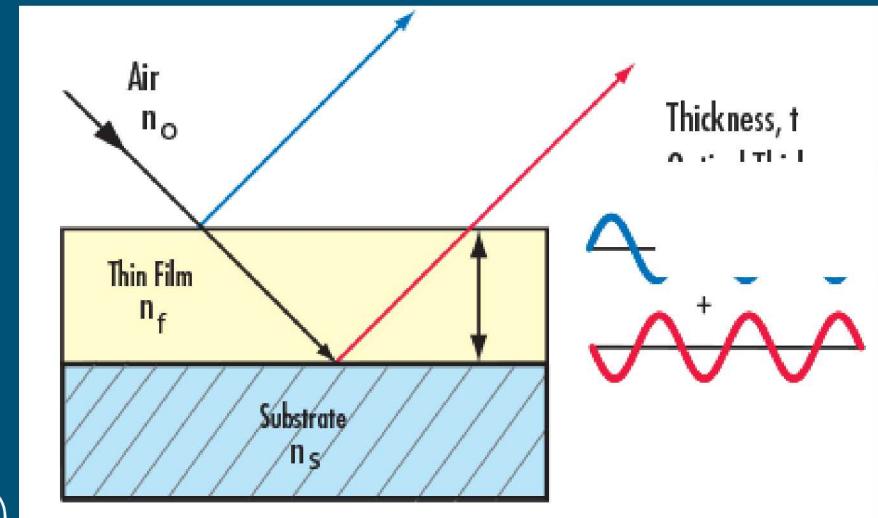
n_s -RI of substrate

n_0 -RI of environment

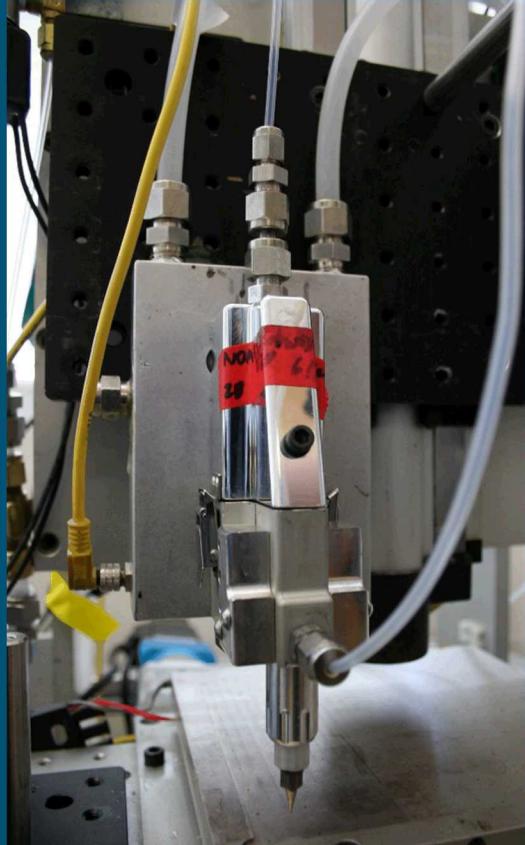
d_f -Film thickness

λ -Wavelength

k-Odd integer (1,3,5,...)



<https://www.edmundoptics.com/resources/application-notes/optics/anti-reflection-coatings/>



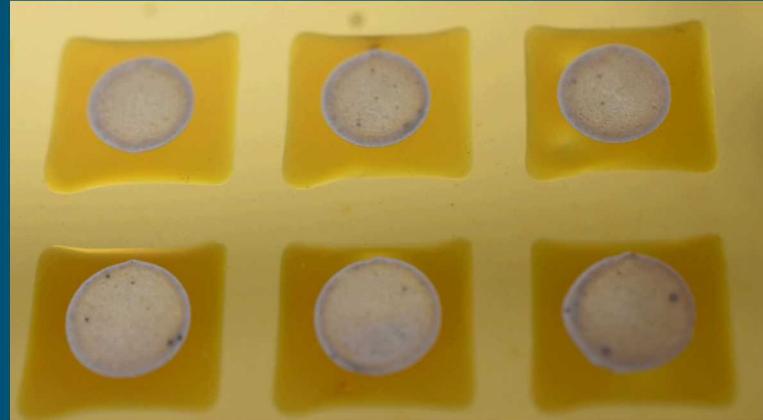
- Aerodynamic focusing of aerosolized materials
 - Conductive nanoparticle inks
 - Dielectric polymers
 - Low viscosity solutions
- Low profile, well focused traces
 - Trace width from 50 to 300 μm
 - Single layer height $< 1 \mu\text{m}$
- Parameters
 - Aerosol flowrate
 - Sheath gas flowrate
 - Atomizer voltage
 - Focusing tip diameter
 - Focusing tip height



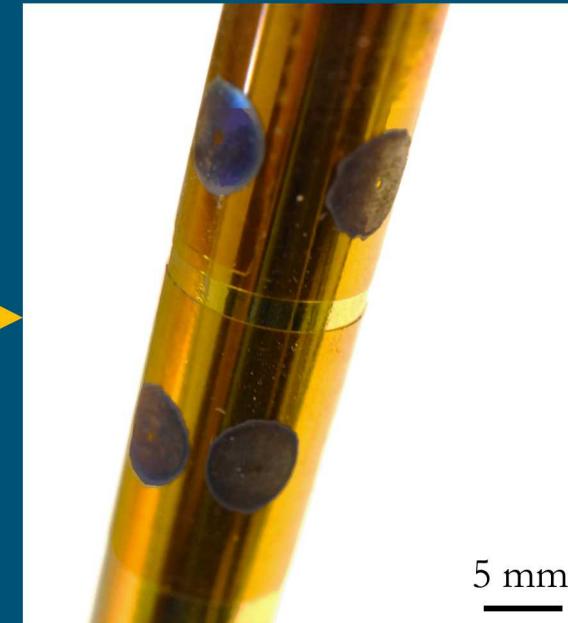
Distribution circuit printed using silver nanoparticle ink

Technical Background – NanoJet Deposition Tool (cont.)

- Tool has been utilized to produce micron-scale electronics
- Capability to produce conformal components and coatings
 - Capacitor printed on perimeter of cylindrical rod
 - Enables selective deposition of materials onto complex, novel structures



Planer capacitor of printed Ag pad, polyimide dielectric, and Au wafer substrate



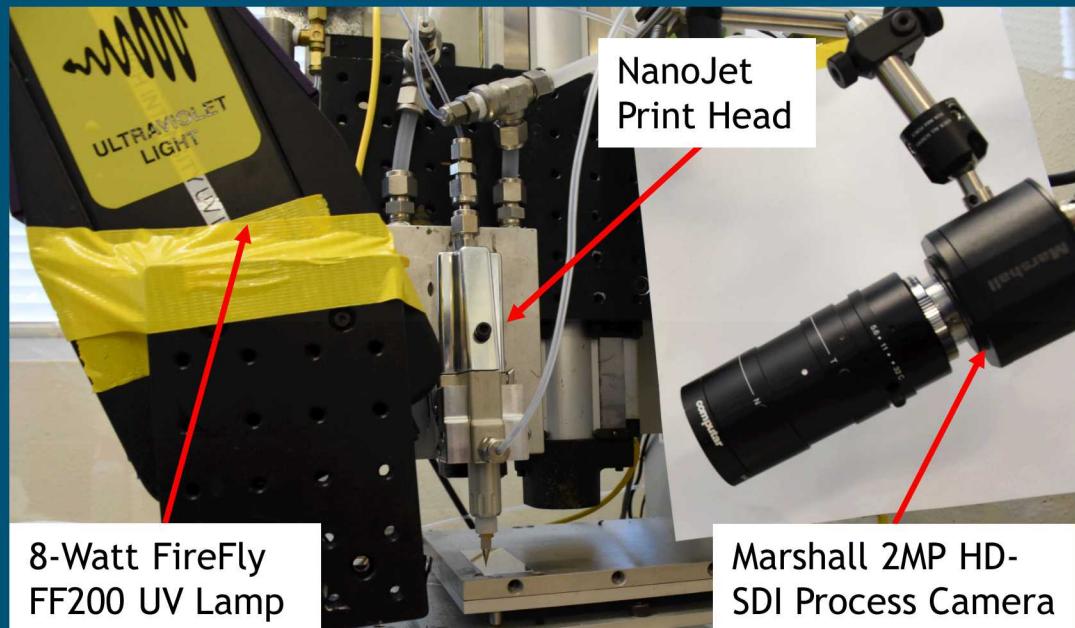
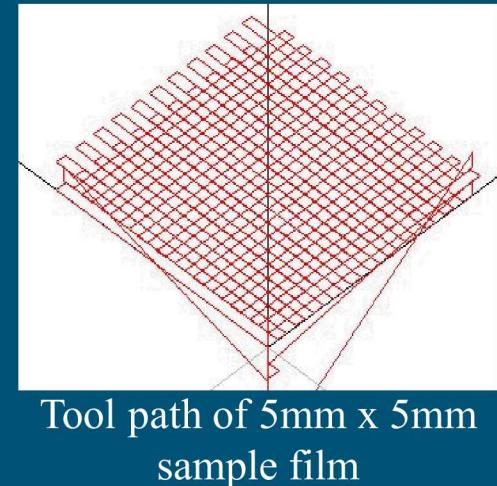
Cylindrical capacitor of printed Ag pad, Kapton dielectric, and Au coated cylindrical substrate

Selected Materials

- Norland Optical Adhesive 89 (NOA 89) utilized as primary film material
 - UV curable material
 - Well established refractive index – 1.51
 - Low viscosity (15-20 cP)
 - Highly transmissive of wavelengths $>\sim 450$ nm
- Isobutyl acetate used as diluting agent
 - Volatile and non-toxic solvent
 - Believed to completely evaporate from solution during atomization or shortly after deposition onto heated substrate
- NOA 89 was diluted with isobutyl acetate to both lower viscosity in order to promote atomization and to decrease deposition rate to deposit thinner films
- Two solutions of these chemicals, mixed at different ratios were tested:
 - 1:14 NOA 89:Isobutyl acetate
 - 1:20 NOA 89:Isobutyl acetate

Experiment Procedure – Deposition Protocol

- Cross-hatched tool path, alternating axis of motion between layers
- UV curing during deposition and between layers to achieve pre-cure of deposited material
- Platen heated to 60°C to drive off solvent
- 335 μ m tip diameter held at 2.5mm above substrate
- Materials deposited onto Si wafer substrate
- Films deposited as 5mm x 5mm test geometries



NanoJet deposition system

Experiment Procedure – Deposition Protocol (cont.)

- Deposition parameters varied depending on concentration of material being deposited

NOA 89:Isobutyl Acetate Concentration	1:14	1:20
Print Speed (mm/min)	220	180
Infill Spacing (mm)	0.140	0.200
Aerosol Flow Rate (sccm)	14.0	12.0
Sheath Flow Rate (sccm)	11.0	10.0
Atomizer Voltage (V)	41.5	45.0
Substrate Temperature (°C)	60	60
UV Lamp Output (% output)	10	30
Time Delay Between Layers (sec)	180	180

Experiment Procedure – Sample Processing

- Three step curing process
 1. Thermal stepping process
 - 60°C - 10 minutes
 - 80°C - 15 minutes
 - 100°C - 10 minutes
 - 120°C - 20 minutes
 2. UV curing
 - 500W, 400nm, $\sim 63\text{mW/cm}^2$ - 30 minutes
 3. Thermal curing
 - 120°C - 30 minutes

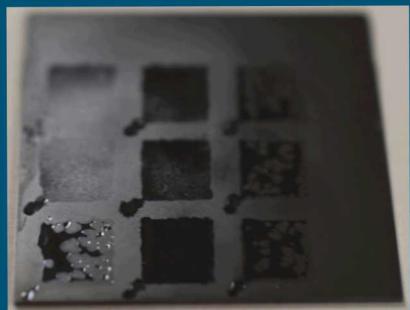
1:14



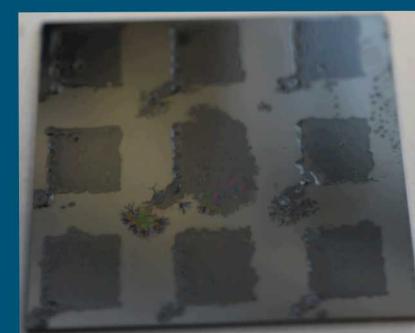
1:20



Prior to Curing



Following Thermal 1 and UV

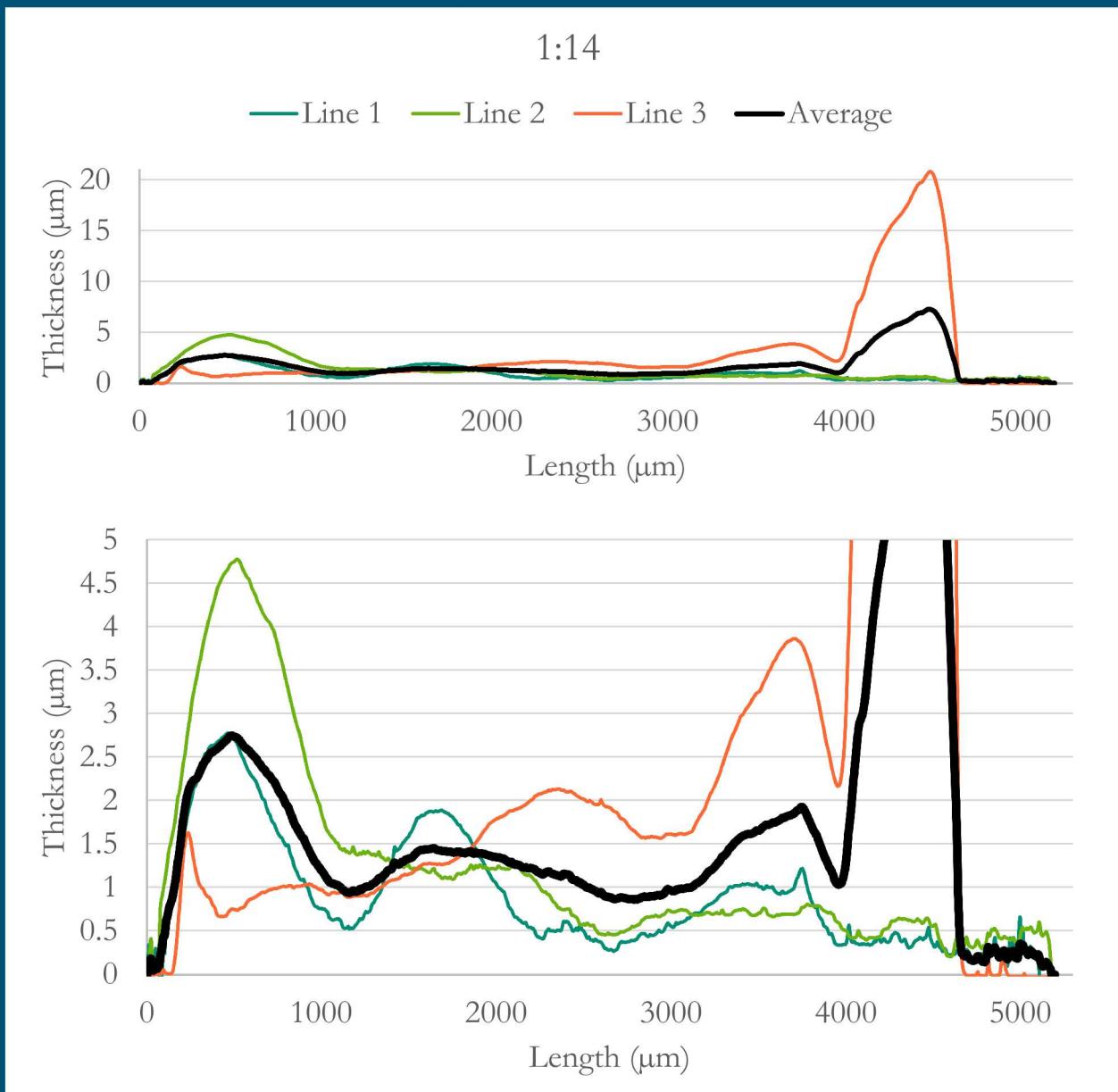


Final Cured Sample

5 mm

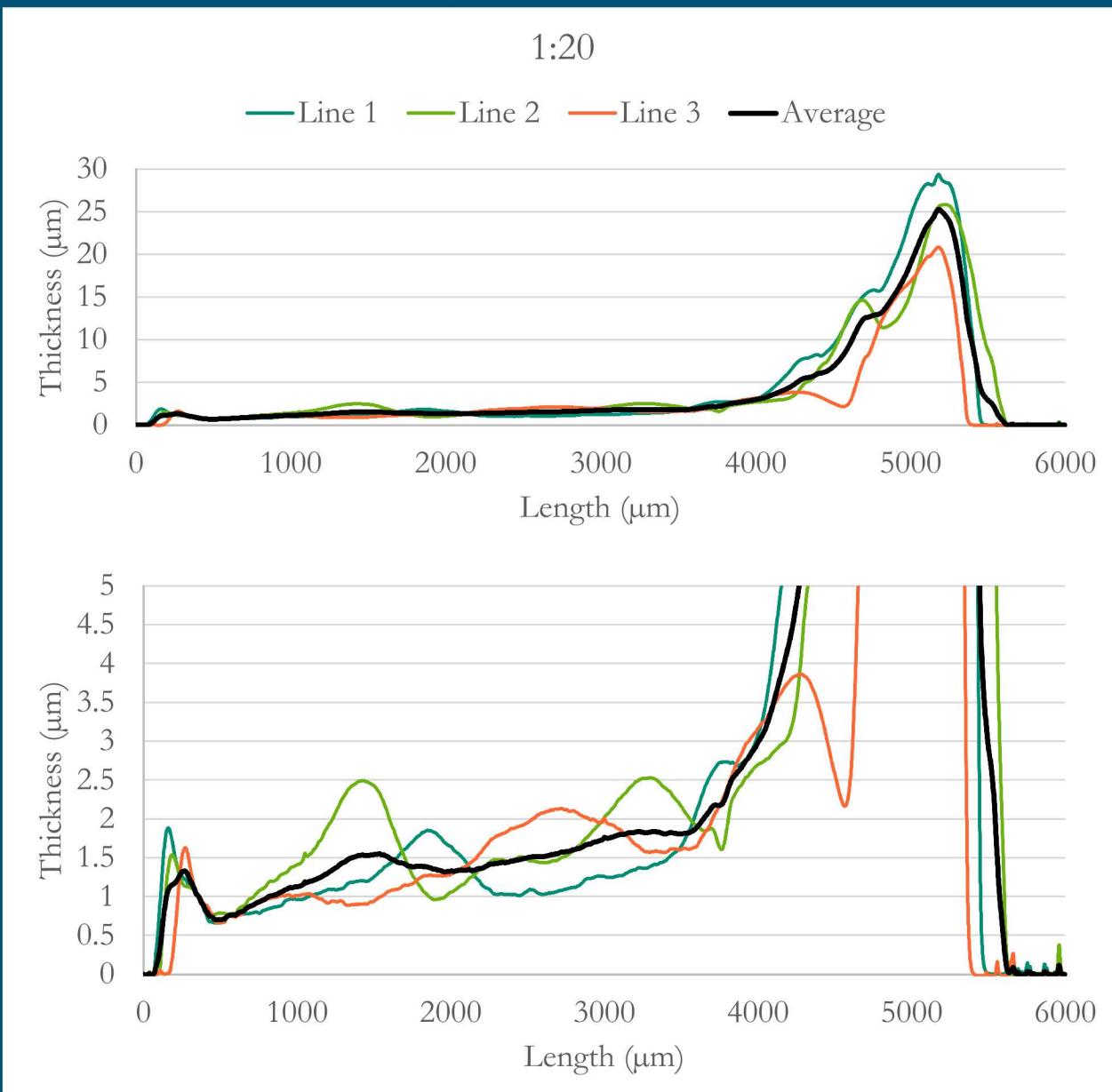
Film Performance – Thickness and Surface Uniformity

- Profilometry performed on cured samples
- Both material concentrations exhibited nonuniform film thickness
 - Both featured at least one peak across the film, likely due to fluid migration during print
- 1:14 concentration demonstrated a thickness on the order of 1 μm , going as low as ~ 500 nm
- 1:20 concentration demonstrated severe slope across film, with thickness between 1 and 2 μm
- Surfaces likely too uneven to reliably serve as optical coatings as is



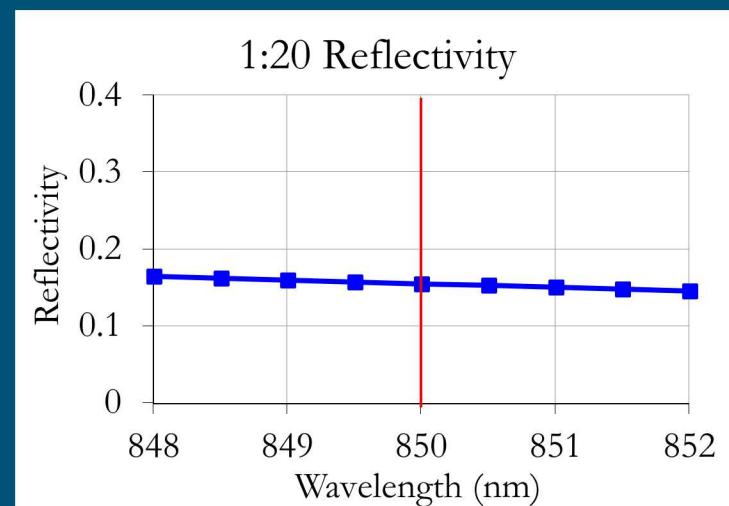
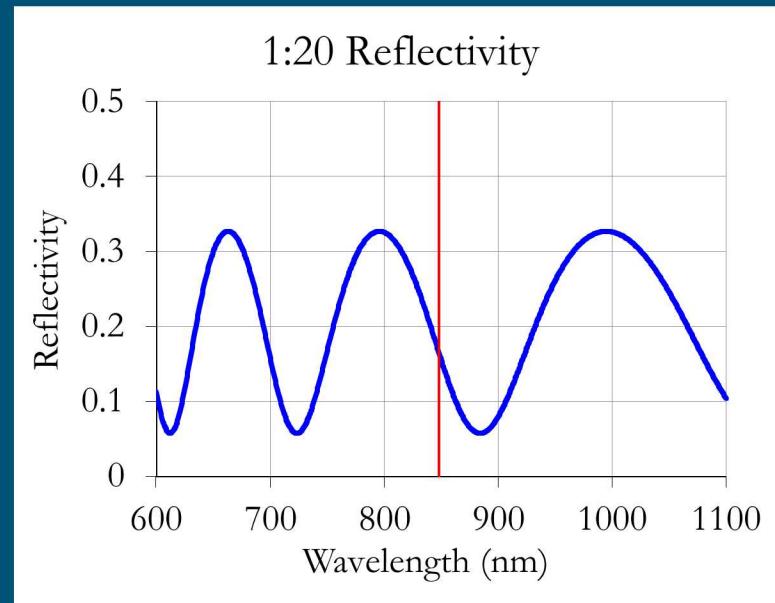
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Film Performance – Reflectivity and Optical Thickness

- 1:14 samples too nonuniform to produce reliable data
- 1:20 sample was tested to measure reflectivity
 - ~20% reflectivity at 850 nm operational wavelength
 - ~7% reflectivity at ~875 nm
- Optical thickness (RI*thickness) measured to be 1989 nm
 - RI of film estimated to be slightly less than that of bulk NOA 89 (1.51 → 1.50)
 - Thickness of film calculated to be 1326 nm, roughly matching profilometry

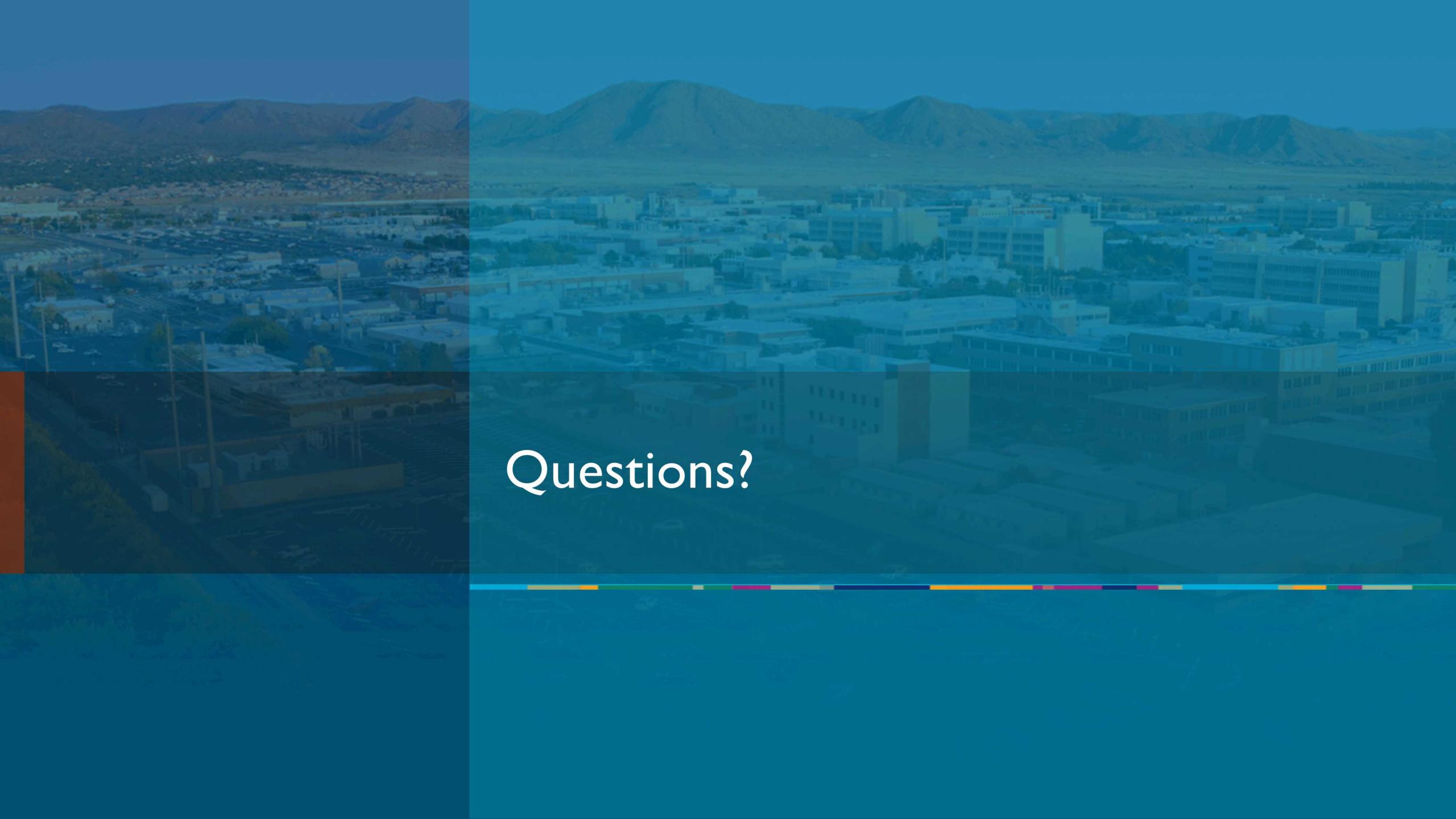


Future Work

- Identify methods of improving surface uniformity
 - Changes in material composition
 - Changes in deposition procedure
- Evaluate methods of improving in-situ curing to prevent material flows during deposition
- Experiment with producing films of different thicknesses for operation at different wavelengths
- Identify alternative materials for film composition
 - Easily tunable refractive index via altering mixing ratios
- Explore feasibility of producing waveguides using current material set

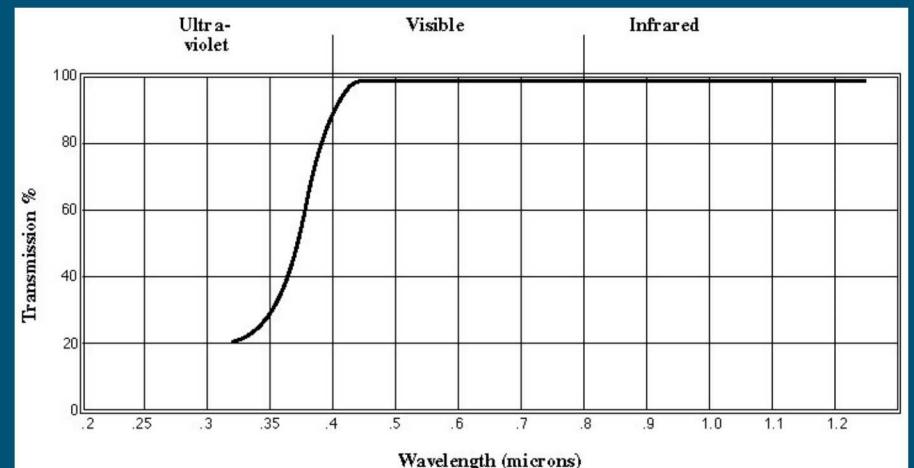
Conclusion

- Demonstrated aerosol jet printing of optical thin films using commercial materials
- Established a multi-stage curing process to simultaneously drive off solvents and harden remaining film material
- Films produced using 1:20 dilution capable of reducing reflectivity to ~20%, could be decreased to <10% if thickness is properly adjusted
- Ongoing work to print optical coatings using additive manufacturing methods

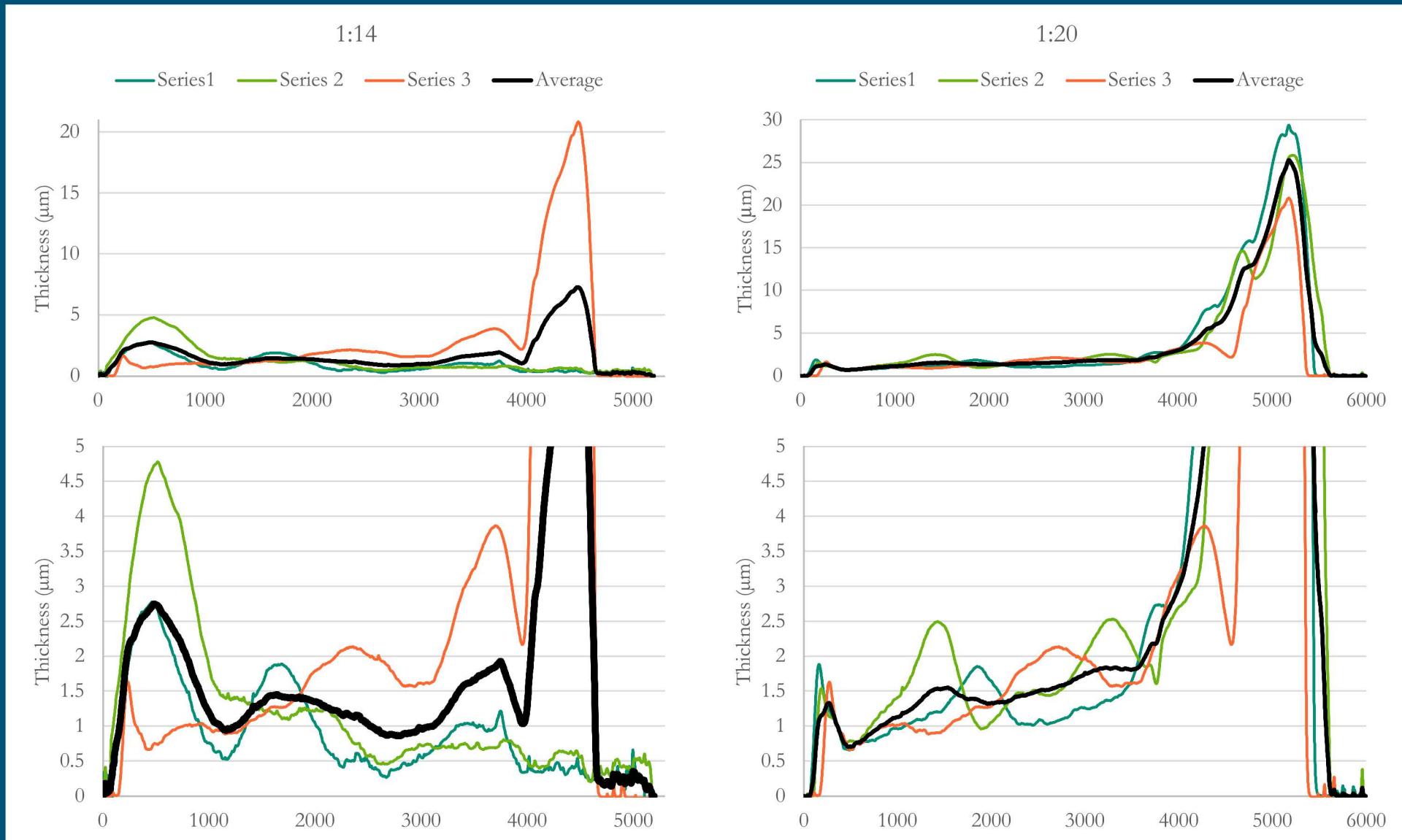


Questions?

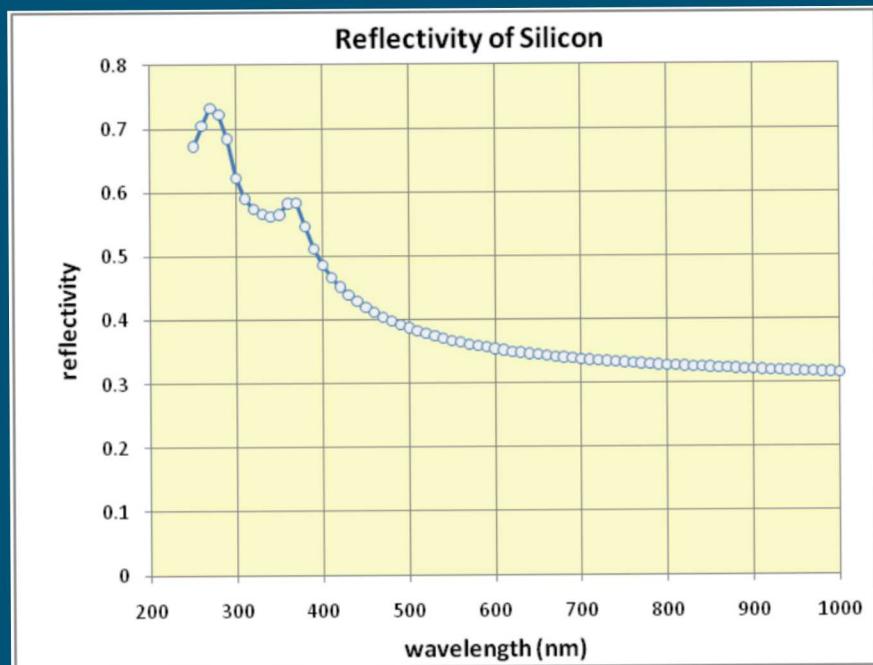
- Reflective Index: 1.51
- Temperature Range: -30°C to 80°C
- Viscosity: 15-20 cps
- Modulus (psi): 4300
- Tensile Strength (psi): 194.5
- Manufacture Recommended Curing Procedure (310-395nm):
 - Precure: 15 seconds under 100 W mercury lamp
 - Final Cure: 5-10 minutes under 100 W mercury lamp



Film Performance – Thickness and Surface Uniformity



Film Performance – Reflectivity and Optical Thickness



<https://www.pveducation.org/pvcdrom/materials/optical-properties-of-silicon>

